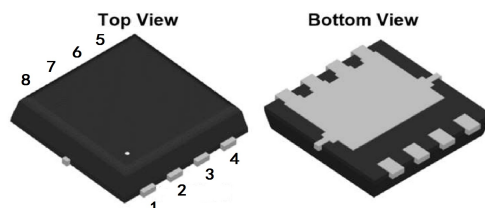


60V N-Channel Mosfet

FEATURES

- $R_{DS(ON)} \leq 8.5m\Omega$ (6.8m Ω Typ.)
@ $V_{GS}=10V$
- $R_{DS(ON)} \leq 15.6m\Omega$ (12m Ω Typ.)
@ $V_{GS}=4.5V$
- AEC Q101 qualified
- Green Product (RoHS compliant)

PDFNWB3.3*3.3-8L



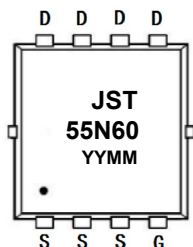
APPLICATIONS

- On board wireless charging
- Motor drivers
- DC - DC Converter

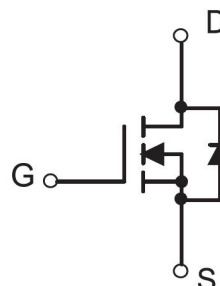
1: S 3: S 5: D 7: D
2: S 4: G 6: D 8: D

N-CHANNEL MOSFET

MARKING



YYMM:Date Code(year & month)



MAXIMUM RATINGS ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Limit.	Units
V_{DSS}	Drain-Source Voltage	60	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current @ $V_{GS}=10V$	40	A
I_{DM}	Pulsed Drain Current ^{note1}	112	A
P_D	Power Dissipation	25	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	6	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	$^\circ\text{C}/\text{W}$
T_J	Operating Temperature	175	$^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +175	$^\circ\text{C}$

MOSFET ELECTRICAL CHARACTERISTICS Tc=25 °C unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =48V, V _{GS} =0V	-	-	1	μA
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	2.0	3.0	V
R _{DS(on)}	Static Drain-Source On-Resistance ^{note2}	V _{GS} =10V, I _D =20A	-	6.8	8.5	mΩ
		V _{GS} =4.5V, I _D =10A	-	12	15.6	
Dynamic Characteristics ^{note3}						
C _{iss}	Input Capacitance	V _{DS} =30V, V _{GS} =0V, f=1.0MHz	-	1362	-	pF
C _{oss}	Output Capacitance		-	581	-	pF
C _{rss}	Reverse Transfer Capacitance		-	44	-	pF
Q _g	Total Gate Charge	V _{DS} =30V, I _D =20A, V _{GS} =10V	-	28	-	nC
Q _{gs}	Gate-Source Charge		-	6	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	7.7	-	nC
Switching Characteristics ^{note3}						
t _{d(on)}	Turn-On Delay Time	V _{DS} =30V, I _D =20A, R _G =4.5Ω, V _{GS} =10V R _L =1.5Ω	-	8	-	ns
t _r	Turn-On Rise Time		-	18	-	ns
t _{d(off)}	Turn-Off Delay Time		-	22	-	ns
t _f	Turn-Off Fall Time		-	11	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	40	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _{SD} =20A, T _J = 25℃	-	-	1.3	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S =20A,	-	61	-	ns
Q _{rr}	Reverse Recovery Charge	di/dt =100A/μs	-	46	-	nC

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

3. Guaranteed by design, not subject to production testing

Typical Performance Characteristics

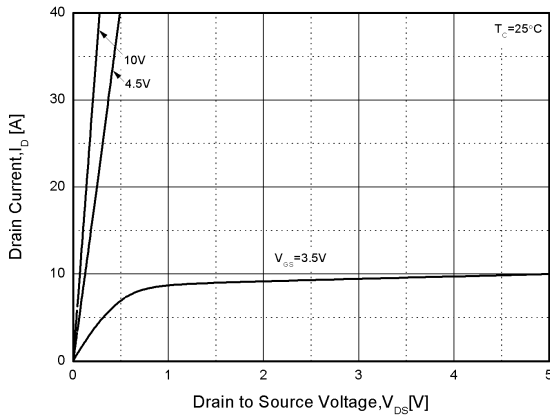


Figure1. Output Characteristics

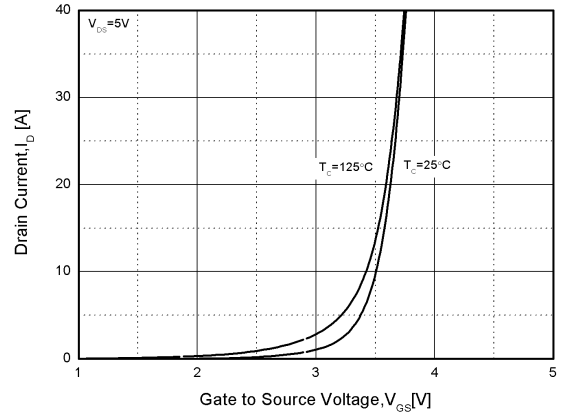


Figure2. Transfer Characteristics

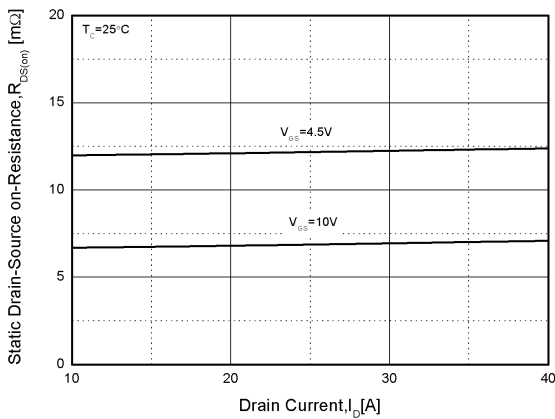


Figure3. Rdson-Drain Current

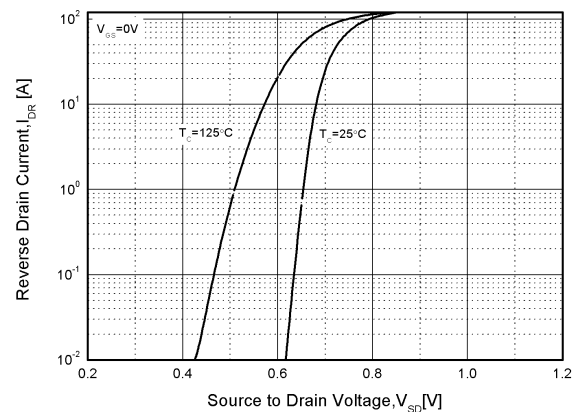


Figure4. Typical Source-Drain Diode Forward Voltage

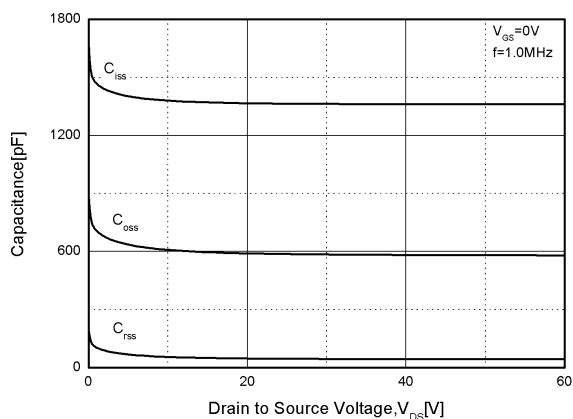


Figure5. Capacitance Characteristics

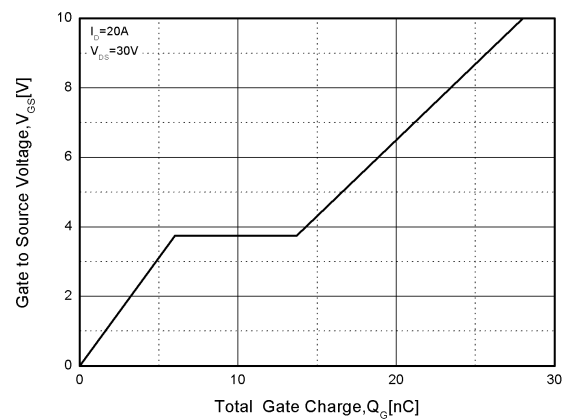


Figure6. Gate Charge

Typical Performance Characteristics (cont.)

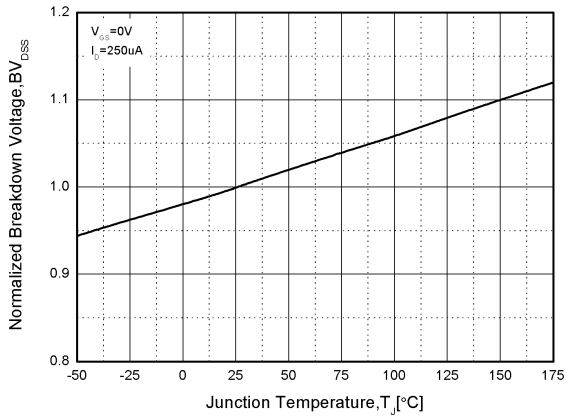


Figure7. Normalized Breakdown Voltage vs. Temperature

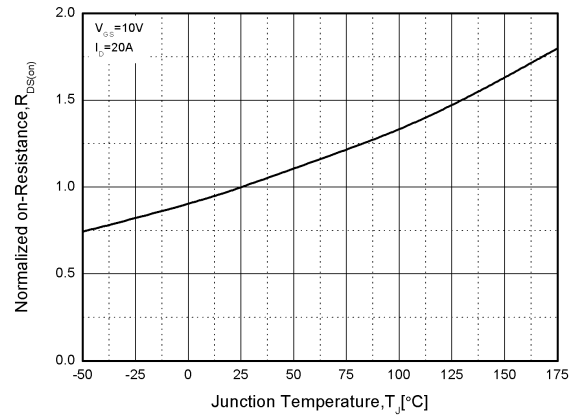


Figure8. Normalized on Resistance vs. Temperature

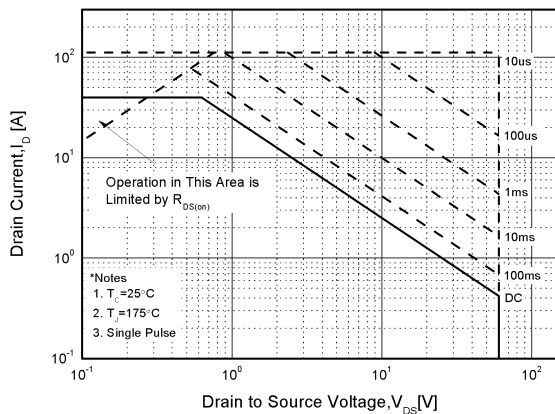


Figure9. Safe Operation Area

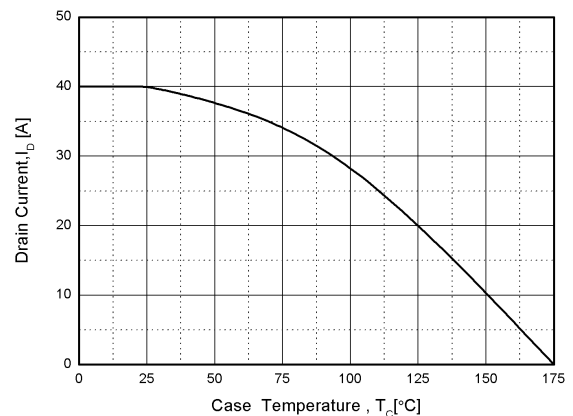


Figure10. Drain Current vs. Case Temperature

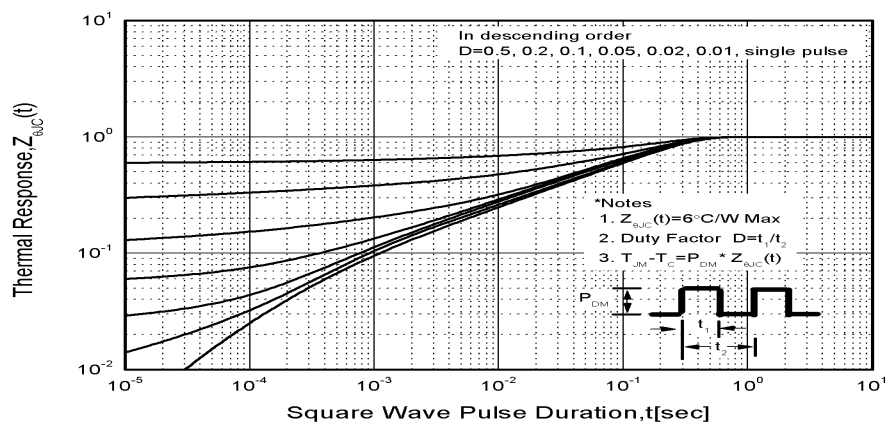
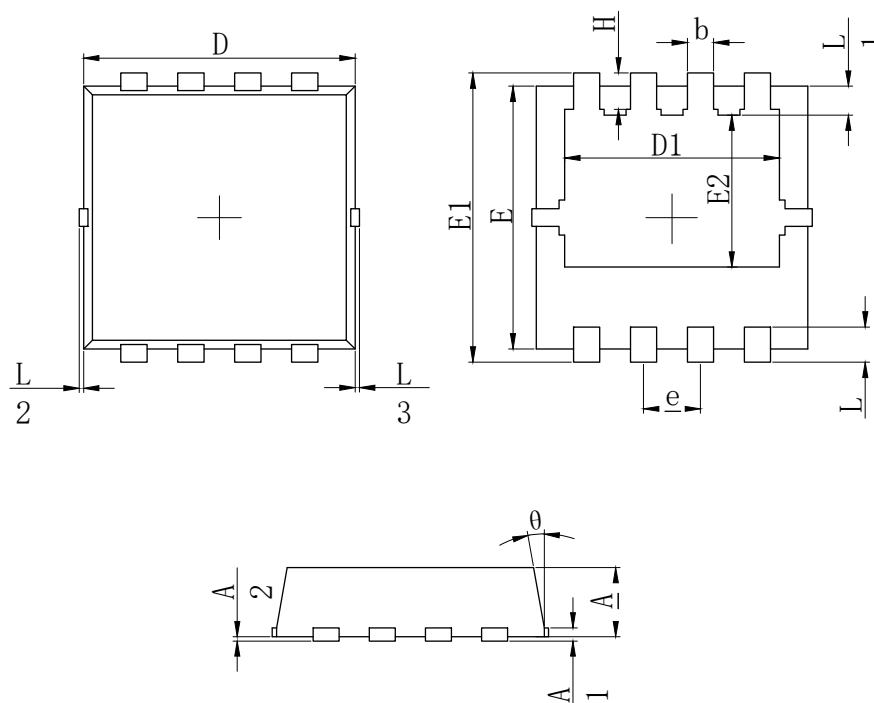


Figure11. Transient Thermal Response Curve

PDFNWB3.3*3.3-8L Package Outline Dimensions



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.700	0.800	0.900
A1	0.152 REF.		
A2	0~0.05		
D	3.000	3.100	3.200
D1	2.300	2.450	2.600
E	2.900	3.000	3.100
E1	3.150	3.300	3.450
E2	1.535	1.735	1.935
b	0.200	0.300	0.400
e	0.550	0.650	0.750
L	0.300	0.400	0.500
L1	0.180	0.330	0.480
L2	0~0.100		
L3	0~0.100		
H	0.315	0.415	0.515
θ	8°	10°	12°